

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,185,307 B2
APPLICATION NO. : 10/708256
DATED : February 27, 2007
INVENTOR(S) : Hsin-Shih Wang

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page item (54), and col. 1, line 1, change

“METHOD OF FABRICATING AND INTEGRATED CIRCUIT THROUGH
UTILIZING METAL LAYERS TO PROGRAM RANDOMLY POSITIONED
BASIC UNITS”

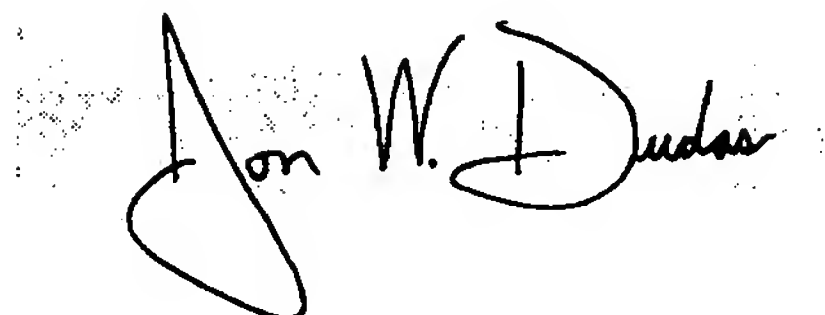
to

--METHOD OF FABRICATING AN INTEGRATED CIRCUIT THROUGH
UTILIZING METAL LAYERS TO PROGRAM RANDOMLY POSITIONED
BASIC UNITS--

Signed and Sealed this

Eighth Day of May, 2007

By _____

A handwritten signature in black ink, reading "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a cursive "Dudas".

JON W. DUDAS
Director of the United States Patent and Trademark Office